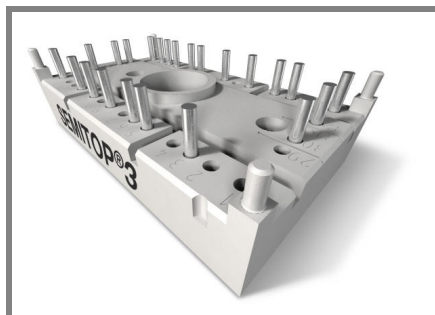




SEMITOP® 3

IGBT Module

SK75GARL065E

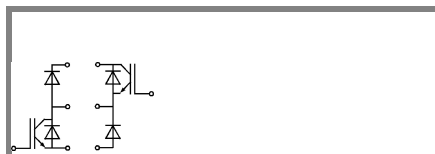
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- N-channel homogeneous silicon structure (NPT-Non punch-through IGBT)
- High short circuit capability
- Low tail current with low temperature dependence

Typical Applications*

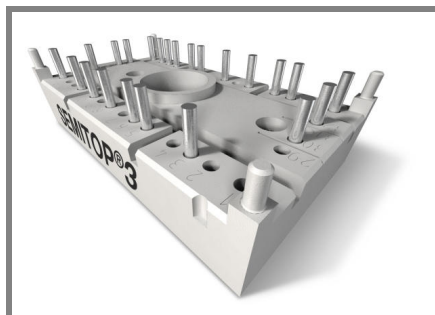
- Switching (not for linear use)
- Switched mode power supplies
- UPS
- Double PFC
- Multilevel inverter



GARL-E

Absolute Maximum Ratings		T _s = 25 °C, unless otherwise specified		
Symbol	Conditions		Values	Units
IGBT				
V _{CES}	T _j = 25 °C		600	V
I _C	T _j = 125 °C	T _s = 25 °C	80	A
		T _s = 80 °C	55	A
I _{CRM}	I _{CRM} = 2 x I _{Cnom}		180	A
V _{GES}			± 20	V
t _{psc}	V _{CC} = 300 V; V _{GE} ≤ 20 V; T _j = 125 °C V _{CES} < 600 V		10	μs
Inverse Diode				
I _F	T _j = 150 °C	T _s = 25 °C	57	A
		T _s = 80 °C	38	A
I _{FRM}	I _{FRM} = 2 x I _{Fnom}			A
I _{FSM}	t _p = 10 ms; half sine wave T _j = 150 °C		440	A
Freewheeling Diode				
I _F	T _j = 150 °C	T _{case} = 25 °C	103	A
		T _{case} = 80 °C	69	A
I _{FRM}	I _{FRM} = 2 x I _{Fnom}			A
I _{FSM}	t _p = 10 ms; half sine wave T _j = 150 °C		880	A
Module				
I _{t(RMS)}				A
T _{vj}			-40 ... +150	°C
T _{stg}			-40 ... +125	°C
V _{isol}	AC, 1 min.		2500	V

Characteristics		$T_s = 25\text{ °C}$, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_C = 2,1\text{ mA}$	3	4	5	V
I_{CES}	$V_{GE} = 600\text{ V}$, $V_{CE} = V_{CES}$ $T_j = 25\text{ °C}$			0,0066	mA
I_{GES}	$V_{CE} = 0\text{ V}$, $V_{GE} = 20\text{ V}$ $T_j = 25\text{ °C}$			360	nA
V_{CE0}				$T_j = 25\text{ °C}$	1,2
				$T_j = 125\text{ °C}$	1,1
r_{CE}	$V_{GE} = 15\text{ V}$			$T_j = 25\text{ °C}$	7,7
				$T_j = 125\text{ °C}$	14
$V_{CE(sat)}$	$I_{Cnom} = 90\text{ A}$, $V_{GE} = 15\text{ V}$			$T_j = 25\text{ °C}_{chiplev.}$	1,7
				$T_j = 125\text{ °C}_{chiplev.}$	2,2
C_{ies}	$V_{CE} = 25$, $V_{GE} = 0\text{ V}$ $f = 1\text{ MHz}$		4,8		nF
C_{oes}			0,45		nF
C_{res}			0,27		nF
Q_G	$V_{GE} = 0 \dots 20\text{ V}$		750		nC
$t_{d(on)}$	$R_{Gon} = 13\text{ }\Omega$	$V_{CC} = 300\text{ V}$ $I_C = 100\text{ A}$	54		ns
t_r			58		ns
E_{on}	$R_{Goff} = 13\text{ }\Omega$	$T_j = 125\text{ °C}$ $V_{GE} = \pm 15\text{ V}$	2,71		mJ
$t_{d(off)}$			410		ns
t_f			36		ns
E_{off}			2,75		mJ
$R_{th(j-s)}$	per IGBT			0,6	K/W



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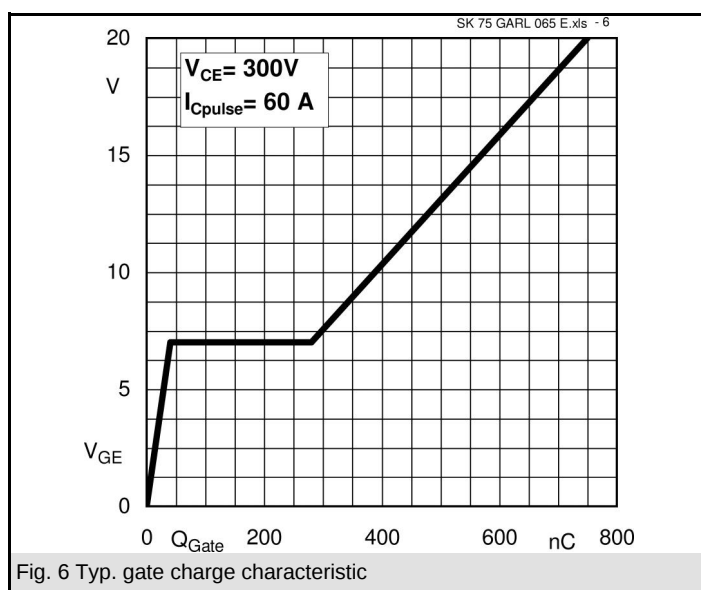
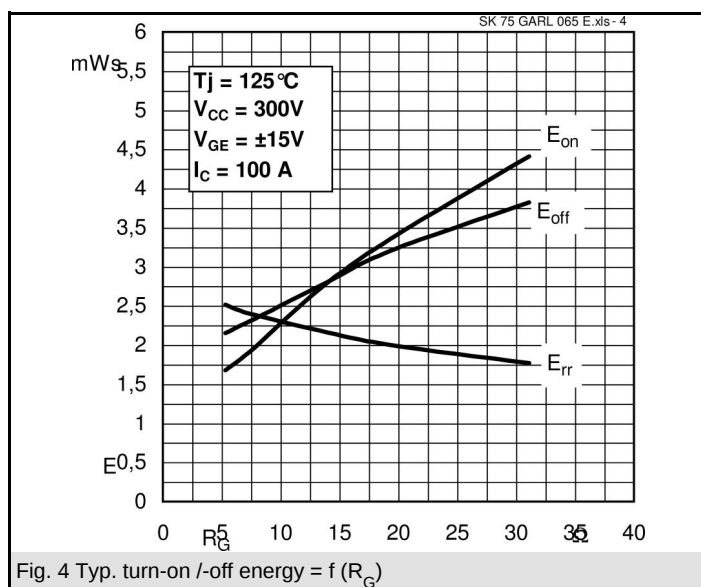
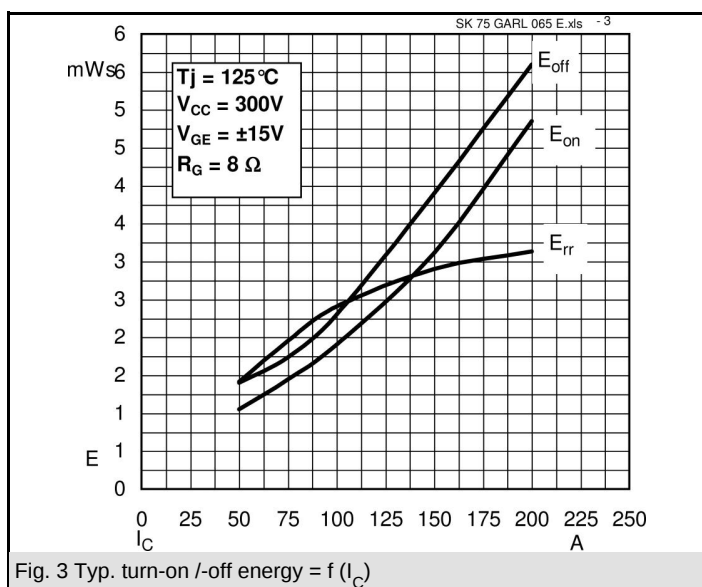
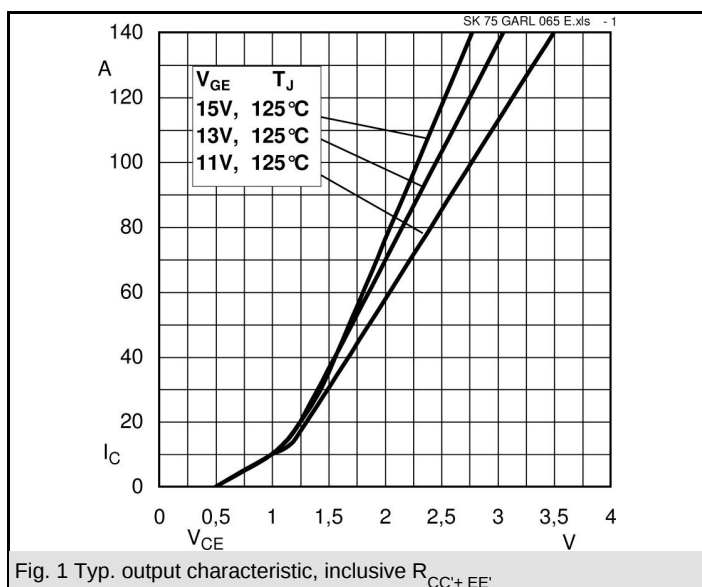


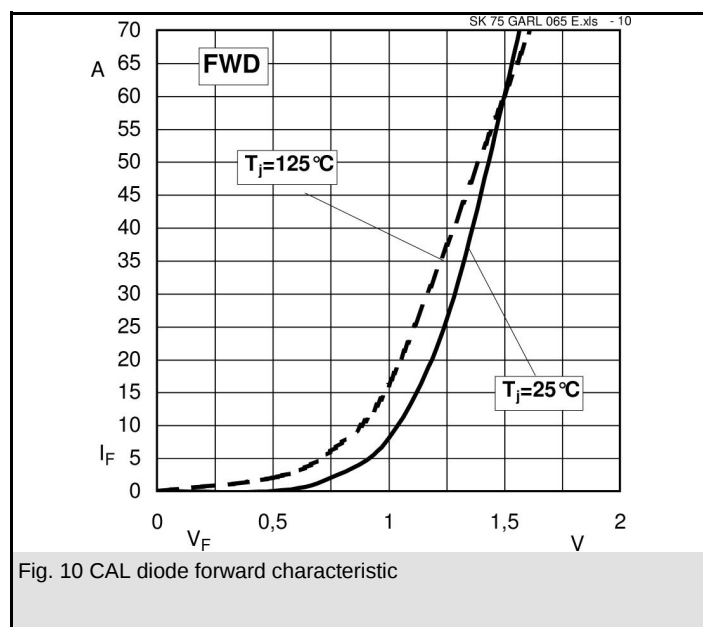
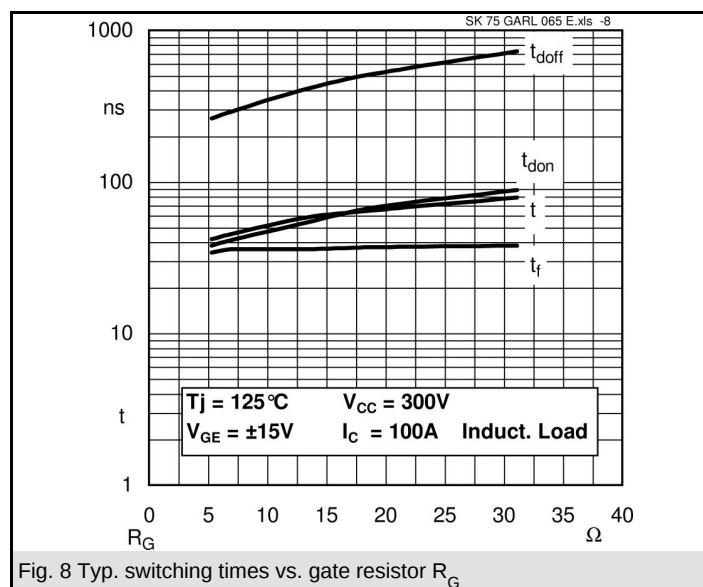
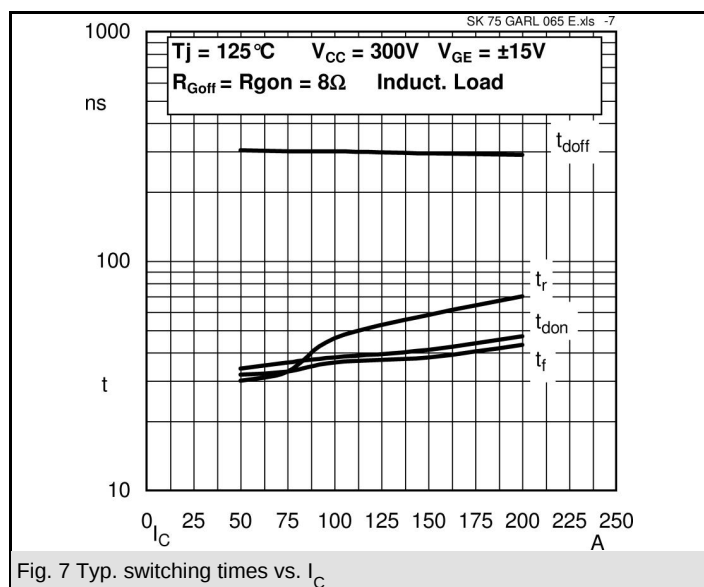
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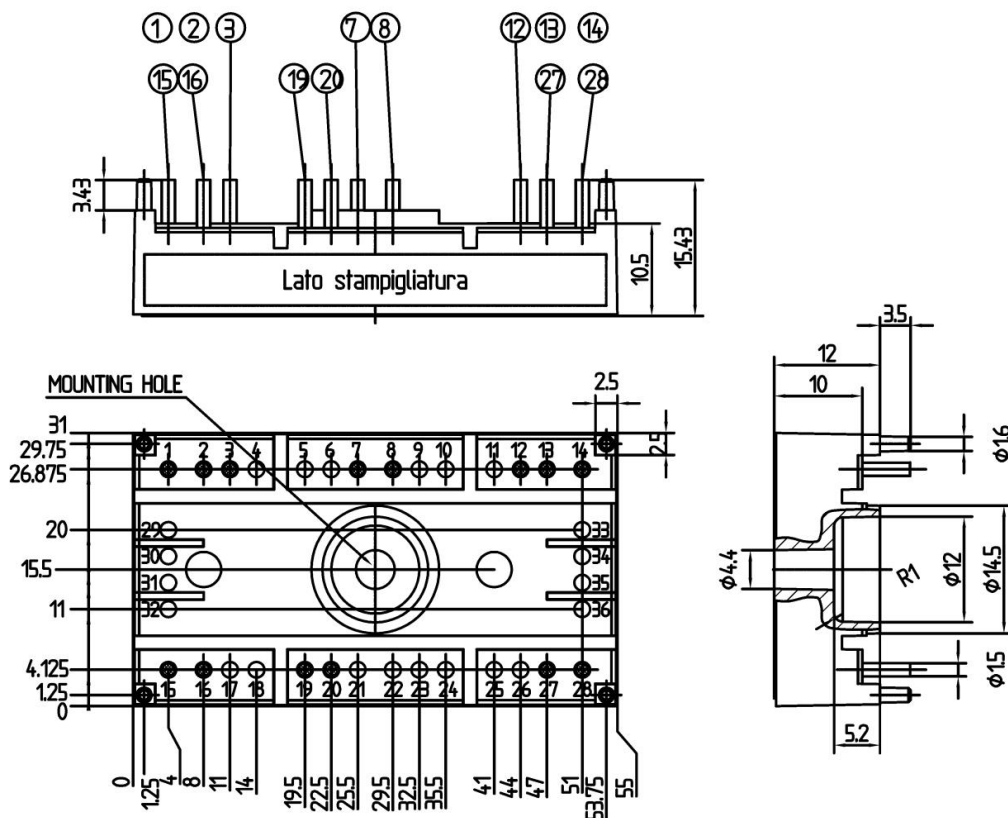
Characteristics					
Symbol	Conditions	min.	typ.	max.	Units
Inverse Diode					
$V_F = V_{EC}$	$I_{Fnom} = 30 \text{ A}; V_{GE} = 0 \text{ V}$				
	$T_j = 25 \text{ }^{\circ}\text{C}_{chiplev.}$		1,3	1,5	V
	$T_j = 125 \text{ }^{\circ}\text{C}_{chiplev.}$		1,2	1,45	V
V_{F0}	$T_j = 125 \text{ }^{\circ}\text{C}$		0,85	0,9	V
r_F	$T_j = 125 \text{ }^{\circ}\text{C}$		9	16	mΩ
I_{RRM}	$I_F = 30 \text{ A}$		22		A
Q_{rr}	$di/dt = -500 \text{ A/}\mu\text{s}$		2,2		μC
E_{rr}	$V_{CC}=300\text{V}$		0,2		mJ
$R_{th(j-s)D}$	per diode			1,2	K/W
Freewheeling diode					
$V_F = V_{EC}$	$I_{Fnom} = 60 \text{ A}; V_{GE} = 0 \text{ V}$				
	$T_j = 25 \text{ }^{\circ}\text{C}_{chiplev.}$		1,45		V
	$T_j = 125 \text{ }^{\circ}\text{C}_{chiplev.}$		1,4		V
V_{F0}	$T_j = 125 \text{ }^{\circ}\text{C}$		0,85	0,9	V
r_F	$T_j = 125 \text{ }^{\circ}\text{C}$		5	9	V
I_{RRM}	$I_F = 100 \text{ A}$		92		A
Q_{rr}	$di/dt = -9200 \text{ A/}\mu\text{s}$		39,1		μC
E_{rr}	$V_R=300\text{V}$		1,85		mJ
$R_{th(j-s)D}$	per diode			0,6	K/W
M_s	to heat sink	2,25		2,5	Nm
w			30		g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

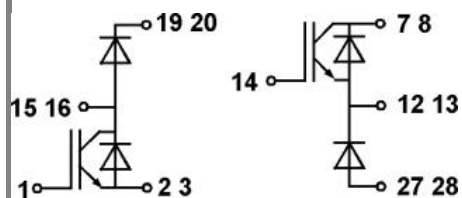
* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.







Case T55 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T55

GARL-E